Power MOSFET

40 V, 1.3 m Ω , 235 A, Single N-Channel

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	40	V
Gate-to-Source Voltage	Gate-to-Source Voltage			±20	V
Continuous Drain		T _C = 25°C	I _D	235	Α
Current R _{θJC} (Notes 1, 3)	Steady	T _C = 100°C		166	
Power Dissipation	State	$T_C = 25^{\circ}C$	P_{D}	128	W
R _{θJC} (Note 1)		T _C = 100°C		64	
Continuous Drain		$T_A = 25^{\circ}C$	I _D	41	Α
Current R _{θJA} (Notes 1, 2, 3)	Steady	T _A = 100°C		29	
Power Dissipation	State	$T_A = 25^{\circ}C$	P_{D}	3.8	W
R _{θJA} (Notes 1 & 2)	R _{0JA} (Notes 1 & 2)			1.9	
Pulsed Drain Current	$T_A = 25^{\circ}C$, $t_p = 10 \mu s$		I _{DM}	900	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to + 175	°C
Source Current (Body Diode)			I _S	122	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 19 A)			E _{AS}	739	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		TL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	1.2	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{ heta JA}$	39	

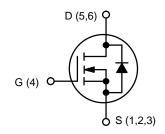
- 1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



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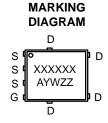
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
40 V	1.3 mΩ @ 10 V	235 A



N-CHANNEL MOSFET



CASE 488AA STYLE 1



XXXXXX = 5C426N

= Assembly Location = Year

W = Work Week = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

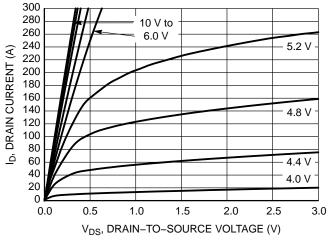
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS				•		•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				9.6		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C			10	
		$V_{DS} = 40 \text{ V}$	T _J = 125°C			100	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V, } V_{GS}$; = 20 V			100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$	= 250 μΑ	2.5		3.5	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-8.6		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 50 A		1.1	1.3	mΩ
Forward Transconductance	9FS	V _{DS} =15 V, I _D	= 50 A		145		S
CHARGES, CAPACITANCES & GATE RE	SISTANCE						
Input Capacitance	C _{ISS}				4300		
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			2100		pF
Reverse Transfer Capacitance	C _{RSS}				59		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 20 V; I _D = 50 A			65		
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V, V _{DS} = 20 V; I _D = 50 A			13		
Gate-to-Source Charge	Q _{GS}				20		nC
Gate-to-Drain Charge	Q_{GD}				12		
Plateau Voltage	V _{GP}				4.7		V
SWITCHING CHARACTERISTICS (Note 5	5)						
Turn-On Delay Time	t _{d(ON)}				15		
Rise Time	t _r	$V_{GS} = 10 V, V_{DS}$	s = 20 V,		47]
Turn-Off Delay Time	t _{d(OFF)}	$I_D = 50 \text{ A}, R_G = 2.5 \Omega$			36		ns -
Fall Time	t _f				9.0		
DRAIN-SOURCE DIODE CHARACTERIS	TICS						
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.82	1.2	
			T _J = 125°C		0.68		- V
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dIS/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 50 \text{ A}$			63		
Charge Time	t _a				34		ns
Discharge Time	t _b				29		
Reverse Recovery Charge	Q_{RR}				92		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.

^{5.} Switching characteristics are independent of operating junction temperatures.

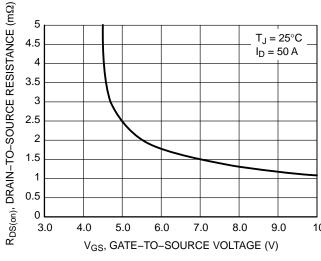
TYPICAL CHARACTERISTICS



300 $V_{DS} = 10 \text{ V}$ 280 260 240 ID, DRAIN CURRENT (A) 220 200 180 160 140 120 100 $T_J = 25^{\circ}C$ 80 60 40 20 $T_J = 125^{\circ}C$ T_J = -55°C 0 7 V_{GS}, GATE-TO-SOURCE VOLTAGE (V)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



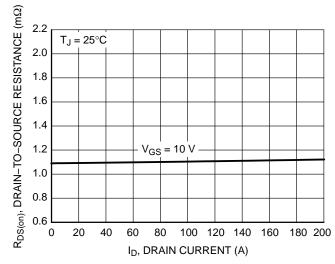
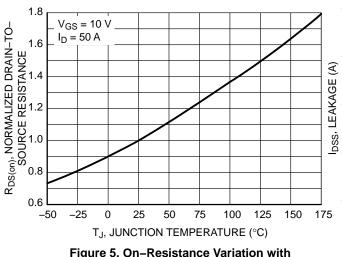


Figure 3. On-Resistance vs. Gate-to-Source Voltage

Figure 4. On-Resistance vs. Drain Current and Gate Voltage



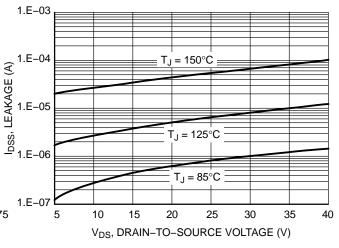


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

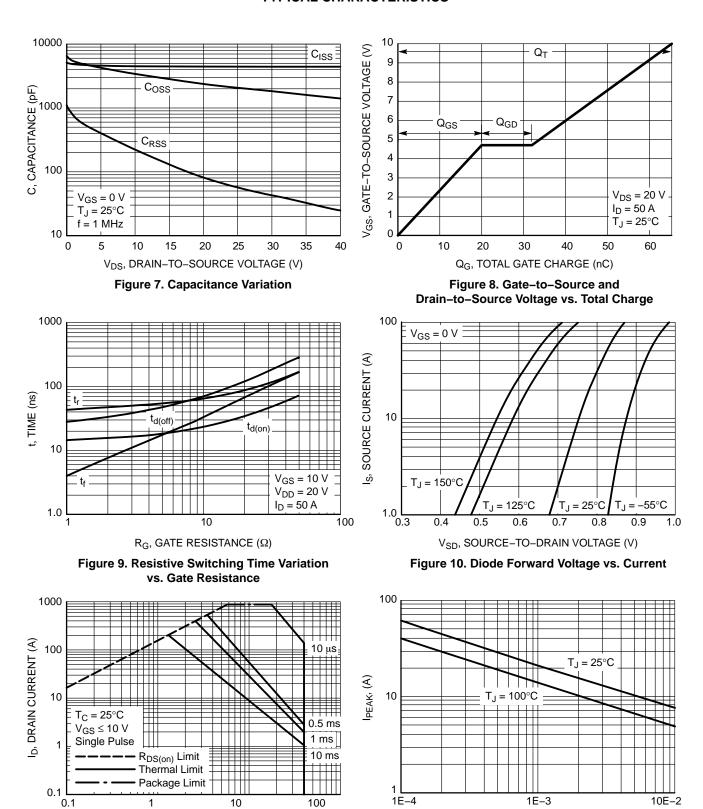


Figure 11. Safe Operating Area Figure 12. I_{PEAK} vs. Time in Avalanche

TIME IN AVALANCHE (s)

V_{DS}, DRAIN-TO-SOURCE VOLTAGE (V)

TYPICAL CHARACTERISTICS

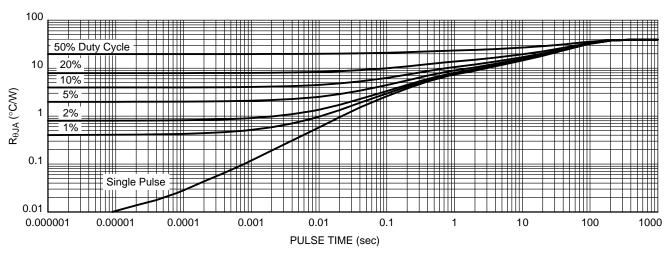


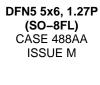
Figure 13. Thermal Characteristics

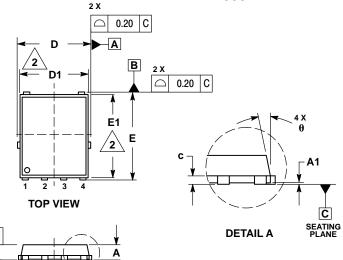
DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS5C426NT1G	5C426N	DFN5 (Pb–Free)	1500 / Tape & Reel
NTMFS5C426NT3G	5C426N	DFN5 (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS





NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- CONTROLLING DIMENSION: MILLIMETER. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
Е	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е	1.27 BSC			
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
М	3.00	3.40	3.80	
θ	0 °		12 °	

- STYLE 1: PIN 1. SOURCE
 - 2. SOURCE 3. SOURCE
 - 4 GATE DRAIN
- **DETAIL A** 0.495 4.560 0.10 С Α В 1.530 Ф 0.05 С 3.200 4.530 1.330 PIN 5 (EXPOSED PAD) 0.905 0.965 D2 G **BOTTOM VIEW** 1.000 1.270 **PITCH** 4X 0.750 →

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DIMENSIONS: MILLIMETERS

RECOMMENDED

SOLDERING FOOTPRINT*

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